

ABSTRACT OF THE DISCLOSURE

The present invention relates to a method of manufacturing an electronic part in which on that side of an insulating member sandwiched between 5 conductor film and a lower conductor layer which is adjacent to the conductor film, a conductor portion connected from the lower conductor layer is exposed. In this method, an opening portion having the lower conductor layer as a bottom is formed on the formed 10 area of the conductor portion from the conductor film side, and metal plating is grown from the bottom of the opening portion with the lower conductor layer as an electrode. After this metal plating has reached the conductor film to thereby form a conductor 15 portion in the opening portion, the metal plating is grown on the upper surfaces of the conductor film and the conductor portion with the conductor film and the conductor portion as electrodes, to thereby form a thickness enough to form an upper conductive layer.